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PRIMA-BOND
EG7635

Ambient Curable
Thermally Conductive
2-Component Epoxy Paste
High Bond Strength

IDEAL FOR:

- Heat-Sink Attach**
- Substrate Attach**
- Component Attach**

DESCRIPTION:

EG7635 is a alumina filled, electrically insulating and thermally conductive rigid epoxy paste adhesive. While bonding at ambient temperature can be achieved overnight, elevated temperatures will accelerate curing, exponentially. EG7635 high thermal conductivity and high strength makes it excellent for bonding substrates, components and heat sinks where thermal management is critical. It has more than 15 years of proven records of providing bonding to difficult substrates. EG7635 exhibits reduced bond strength at 80-100°C for easier rework.

AVAILABILITY:

EG7635 is available in syringes for automatic needle dispense applications or in jars. Upon request, the material can be shipped premixed and frozen. .

APPLICATION PROCEDURES:

- (1) Store Part A and Part B at ambient.
- (2) Mix A and B 1:1 by weight or volume.
- (3) Cure according to one of the recommended schedules.

**If the material is premixed and frozen, thaw for 30 minutes and apply cure according to one of the recommended cure schedules.

TYPICAL PROPERTIES*

Electrical Resistivity (150 °C/ 60 minutes)	>1X10 ¹⁴ ohm-cm
Dielectric Strength (Volts/mil)	> 750
Glass Transition Temp.(°C)	60
Current Carrying Capabilities	N/A
Lap-Shear Strength	>1000 psi >6.9 N/mm ²
Device Push-off Strength	>1500 psi >10.3 N/mm ²
Cured Density (gm/cc)	2.3
Thermal Conductivity	12 Btu-in/hr-ft ² -°F 1.7 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	45
Maximum Continuous Operation Temp. (°C)	150
Avg. Viscosity(0.5 rpm, 24°C) (Brookfield DV-1, spindle CP51)	304,000 cp

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

****CURE SCHEDULES:**

Temperature	Time
25°C	24 hr
150°C	10 min

SHELF LIFE:

Storage temperature	Shelf Life
25°C	***1 yr from ship date

***Shelf life is for unmixed components. If premixed:-40°C for 6 months. Pot life is 4 hours at 25°C, after mixing.** Mixed components gel, an additional 80°C at 30 min. is suggested for complete cure.

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